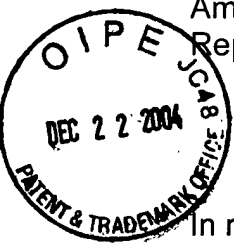


DFW

Appl. No. 10/758,315
Amdt. dated 12/20/2004
Reply to Office Action of 9/22/2004

Attorney Docket No.: N1085-90112
TS03-281



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: **Shih-Yen Tsai**

Examiner: **Sarkar, Asok K.**

Serial No.: **10/758,315**

Group Art Unit: **2829**

Filed: **1/15/2004**

Confirmation No.: **5376**

**For: SOLUTION FOR COPPER HILLOCK INDUCED BY THERMAL STRAIN WITH
BUFFER ZONE FOR STRAIN RELAXATION**

I hereby certify that this document (and any documents referred to therein) are being sent by facsimile to
(703) 872-9306 addressed to the following

Examiner Asok K. Sarkar
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Date: 12/20/04
Maria E. Provencio
Maria E. Provencio

Examiner Asok K. Sarkar
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO OFFICE ACTION DATED 9/22/04

Sir:

Responsive to the Office Action dated September 22, 2004, please re-examine
and reconsider the above-identified application according to the amendments and
remarks provided.

Amendments to the claims are reflected in the listing of claims which begins on
page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.